

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chuen Rong Leu et al.
Assignee: Bridge Semiconductor Corporation
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP
ASSEMBLY WITH AN EMBEDDED METAL PILLAR
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: BDG024-1

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.

The Title Amendments begin on page 2.

The Abstract Amendments begin on page 3.

The Specification Amendments begin on page 4.

The Claim Amendments begin on page 5.

The Remarks begin on page 42.

TITLE AMENDMENTS

Replace the Title with the following:

METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN
EMBEDDED METAL PILLAR